In the Claims

This listing of claims will replace all prior versions, and listings, of claims.

Listing of Claims

1. (Currently Amended):   A reliability assessment system <u>for assessing a reliability of a semiconductor product</u>, comprising:

an interface to receive <u>a selection of an assessment item for the semiconductor product, and</u> input items <u>corresponding to the assessment item, wherein the assessment item comprises a manufacturing process for the semiconductor product</u>; and

an assessment engine to perform a reliability assessment <u>for the semiconductor product toward the assessment item</u> according~~ly~~ <u>to the input items and the manufacturing process</u>, generate a result of the reliability assessment, and display the result on the interface<u>, wherein the result comprises at least one output item corresponding to the assessment item</u>.

2. (Original): The system of claim 1 wherein the interface is a web-based interface.

3. (Original): The system of claim 1 wherein the assessment engine further writes the input items and the corresponding result to a database.

4. (Original): The system of claim 1 further comprising an email server.

5-7. (Cancelled).

8. (Currently Amended):   The system of claim 7 wherein the process comprises GOI (gate oxide integrity), HCI (hot carrier injection), NBTI (negative bias temperature instability), EM (electromigration) or IMD(intermetal dielectirc)-TDDB (time dependent dielectric breakdown).

9-10. (Cancelled).

11. (Currently Amended):   The system of claim 9 1 wherein the assessment item comprises EFR (early failure rate), LTFR (long term failure rate), overdrive, overshoot, or temperature of the semiconductor product.

12. (Currently Amended):   The system of claim 1 wherein the input items comprise technology and specifications of a the semiconductor product.

13. (Cancelled).

14. (Currently Amended):   The system of claim 13 12 wherein the technology is geometry of the semiconductor product.

15. (Currently Amended): The system of claim ~~13~~ <u>12</u> wherein the specification comprises parameters comprising at least a voltage and a lifetime of the semiconductor product.

16. (Currently Amended): A computerized reliability assessment method <u>for assessing a reliability of a semiconductor product</u>, comprising the steps of:

receiving <u>a selection of an assessment item for the semiconductor product, and</u> input items <u>corresponding to the assessment item</u> through a web-based interface<u>, wherein the assessment item comprises a manufacturing process for the semiconductor product</u>;

performing a reliability assessment <u>for the semiconductor product toward the assessment item</u> according~~ly~~ <u>to the input items and the manufacturing process</u>; and

generating a result of the reliability assessment<u>, wherein the result comprises at least one output item corresponding to the assessment item</u>.

17. (Original): The method of claim 16 further comprising displaying the result on the web-based interface.

18. (Original): The method of claim 16 further comprising writing the input items and the corresponding result to a database.

19. (Original): The method of claim 16 further comprising sending an email notification.

20-22. (Cancelled).

23. (Currently Amended):   The method of claim 22 wherein the process comprises GOI (gate oxide integrity), HCI (hot carrier injection), NBTI (negative bias temperature instability), EM (electromigration) or IMD(intermetal dielectirc)-TDDB (time dependent dielectric breakdown).

24-25. (Cancelled).

26. (Currently Amended):   The method of claim ~~24~~ 16 wherein the assessment item comprises EFR (early failure rate), LTFR (long term failure rate), overdrive, overshoot, or temperature of the semiconductor product.

27. (Currently Amended):   The method of claim 16 wherein the input items comprise technology and specifications of ~~a~~ the semiconductor product.

28. (Cancelled).

29. (Currently Amended):   The method of claim ~~28~~ 27 wherein the technology is geometry of the semiconductor product.

30. (Currently Amended):   The method of claim ~~28~~ <u>27</u> wherein the specification comprises parameters comprising at least a voltage and a lifetime of the semiconductor product.

31. (Currently Amended):   A machine-readable storage medium storing a computer program which, when executed, directs a computer to perform a method of reliability assessment <u>for assessing a reliability of a semiconductor product</u>, comprising the steps of:

      receiving <u>a selection of an assessment item for the semiconductor product, and</u> input items <u>corresponding to the assessment item</u> through a web-based interface<u>, wherein the assessment item comprises a manufacturing process for the semiconductor product</u>;

      performing a reliability assessment <u>for the semiconductor product toward the assessment item</u> according~~ly~~ <u>to the input items and the manufacturing process</u>; and

      generating a result of the reliability assessment<u>, wherein the result comprises at least one output item corresponding to the assessment item</u>.

32. (Currently Amended):   The storage medium of claim 31 <u>wherein the method</u> further ~~comprising~~ <u>comprises</u> displaying the result on the web-based interface.

33. (Currently Amended):   The storage medium of claim 31 <u>wherein the method</u> further ~~comprising~~ <u>comprises</u> writing the input items and the corresponding result to a database.

34. (Currently Amended):   The storage medium of claim 31 <u>wherein the method</u> further ~~comprising~~ <u>comprises</u> sending an email notification.

35-37. (Cancelled).

38. (Currently Amended):   The storage medium of claim 37 wherein the process comprises GOI <u>(gate oxide integrity)</u>, HCI <u>(hot carrier injection)</u>, NBTI <u>(negative bias temperature instability)</u>, EM <u>(electromigration)</u> or IMD<u>(intermetal dielectirc)</u>-TDDB <u>(time dependent dielectric breakdown)</u>.

39-40. (Cancelled).

41. (Currently Amended):   The storage medium of claim ~~39~~ <u>31</u> wherein the assessment item comprises EFR (early failure rate), LTFR (long term failure rate), overdrive, overshoot, or temperature of the <u>semiconductor</u> product.

42. (Currently Amended):   The storage medium of claim 31 wherein the input items comprise technology and specifications of ~~a~~ <u>the semiconductor</u> product.

43. (Cancelled).

44. (Currently Amended):   The storage medium of claim 43 42 wherein the technology is geometry of the semiconductor product.

45. (Currently Amended):   The storage medium of claim 43 42 wherein the specification comprises parameters further comprising at least a voltage and a lifetime of the semiconductor product.

46-52. (Cancelled).

53. (Currently Amended):   A set of application program interfaces embodied on a computer-readable medium for execution on a computer in conjunction with an application program that performs a reliability assessment for assessing a reliability of a semiconductor product, comprising:

    a first interface to receive a selection of an assessment item for the

        semiconductor product, and input items corresponding to the assessment

        item of a reliability inquiry; and

    a second interface to display a result of the reliability assessment, in which the

        result comprises at least one output item corresponding to the

        assessment item, and the result is generated accordingly to a reliability

        assessment for the semiconductor product toward the assessment item

        based on the input items and the manufacturing process.

54-55. (Cancelled).